

## Quad 2-Input Multiplexer with Three-State Outputs

### Features

- 'AC257, 'ACT257..... Non-Inverting Outputs
  - CD74ACT258 ..... Inverting Outputs
  - Buffered Inputs
  - Typical Propagation Delay
    - 4.4ns at  $V_{CC} = 5V$ ,  $T_A = 25^{\circ}C$ ,  $C_L = 50pF$
  - Exceeds 2kV ESD Protection MIL-STD-883, Method 3015
  - SCR-Latchup-Resistant CMOS Process and Circuit Design
  - Speed of Bipolar FAST™/AS/S with Significantly Reduced Power Consumption
  - Balanced Propagation Delays
  - AC Types Feature 1.5V to 5.5V Operation and Balanced Noise Immunity at 30% of the Supply
  - $\pm 24mA$  Output Drive Current
    - Fanout to 15 FAST™ ICs
- Drives 50Ω Transmission Lines

### Description

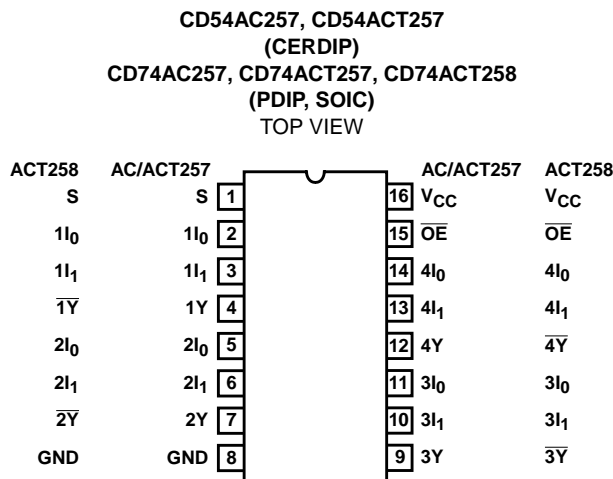
The 'AC257, 'ACT257 and CD74ACT258 are quad 2-input multiplexers with three-state outputs that utilize Advanced CMOS Logic technology. Each of these devices selects four bits of data from two sources under the control of a common Select input (S). The Output Enable ( $\overline{OE}$ ) is active LOW. When  $\overline{OE}$  is HIGH, all of the outputs (Y or  $\overline{Y}$ ) are in the high-impedance state regardless of all other input conditions.

Moving data from two groups of registers to four common output buses is a common use of the 'AC257, 'ACT257, and CD74ACT258. The state of the Select input determines the particular register from which the data comes. The 'AC257, 'ACT257 and CD74ACT258 can also be used as function generators.

### Ordering Information

PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD54AC257F3A	-55 to 125	16 Ld CERDIP
CD74AC257E	0 to 70°C, -40 to 85, -55 to 125	16 Ld PDIP
CD74AC257M	0 to 70°C, -40 to 85, -55 to 125	16 Ld SOIC
CD54ACT257F3A	-55 to 125	16 Ld CERDIP
CD74ACT257E	0 to 70°C, -40 to 85, -55 to 125	16 Ld PDIP
CD74ACT257M	0 to 70°C, -40 to 85, -55 to 125	16 Ld SOIC
CD74ACT258E	0 to 70°C, -40 to 85, -55 to 125	16 Ld PDIP
CD74ACT258M	0 to 70°C, -40 to 85, -55 to 125	16 Ld SOIC

### Pinout

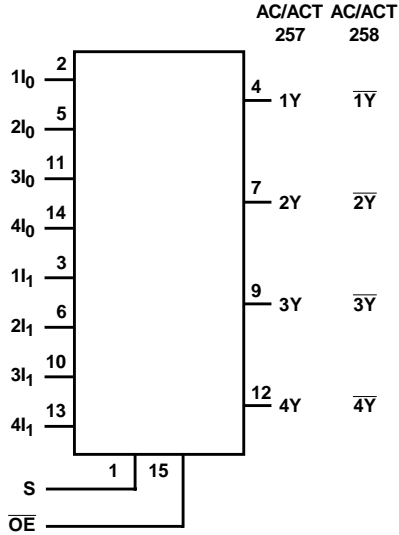


#### NOTES:

1. When ordering, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.
2. Wafer and die for this part number is available which meets all electrical specifications. Please contact your local TI sales office or customer service for ordering information.

**CD54/74AC257, CD54/74ACT257, CD74ACT258**

**Functional Diagram**



**TRUTH TABLE**

OUTPUT ENABLE	SELECT INPUT	DATA INPUTS		257 OUTPUTS	258 OUTPUTS
$\overline{OE}$	S	$I_0$	$I_1$	Y	$\overline{Y}$
H	X	X	X	Z	Z
L	L	L	X	L	H
L	L	H	X	H	L
L	H	X	L	L	H
L	H	X	H	H	L

H = High level voltage, L = Low level voltage, Z = High impedance (off) state, X = Don't Care

## CD54/74AC257, CD54/74ACT257, CD74ACT258

### Absolute Maximum Ratings

DC Supply Voltage, $V_{CC}$ .....	-0.5V to 6V
DC Input Diode Current, $I_{IK}$	
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$ .....	$\pm 20mA$
DC Output Diode Current, $I_{OK}$	
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$ .....	$\pm 50mA$
DC Output Source or Sink Current per Output Pin, $I_O$	
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$ .....	$\pm 50mA$
DC $V_{CC}$ or Ground Current, $I_{CC}$ or $I_{GND}$ (Note 3) .....	$\pm 100mA$

### Thermal Information

Thermal Resistance (Typical, Note 5)	$\theta_{JA}$ ( $^{\circ}C/W$ )
PDIP Package .....	—
SOIC Package .....	—
Maximum Junction Temperature (Plastic Package) .....	$150^{\circ}C$
Maximum Storage Temperature Range .....	$-65^{\circ}C$ to $150^{\circ}C$
Maximum Lead Temperature (Soldering 10s) .....	$300^{\circ}C$

### Operating Conditions

Temperature Range, $T_A$ .....	$-55^{\circ}C$ to $125^{\circ}C$
Supply Voltage Range, $V_{CC}$ (Note 4)	
AC Types .....	1.5V to 5.5V
ACT Types .....	4.5V to 5.5V
DC Input or Output Voltage, $V_I$ , $V_O$ .....	0V to $V_{CC}$
Input Rise and Fall Slew Rate, $dt/dv$	
AC Types, 1.5V to 3V .....	50ns (Max)
AC Types, 3.6V to 5.5V .....	20ns (Max)
ACT Types, 4.5V to 5.5V .....	10ns (Max)

*CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.*

#### NOTES:

3. For up to 4 outputs per device, add  $\pm 25mA$  for each additional output.
4. Unless otherwise specified, all voltages are referenced to ground.
5.  $\theta_{JA}$  is measured with the component mounted on an evaluation PC board in free air.

### DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		$V_{CC}$ (V)	25 $^{\circ}C$		-40 $^{\circ}C$ TO 85 $^{\circ}C$		-55 $^{\circ}C$ TO 125 $^{\circ}C$		UNITS	
		$V_I$ (V)	$I_O$ (mA)		MIN	MAX	MIN	MAX	MIN	MAX		
<b>AC TYPES</b>												
High Level Input Voltage	$V_{IH}$	-	-	1.5	1.2	-	1.2	-	1.2	-	V	
				3	2.1	-	2.1	-	2.1	-	V	
				5.5	3.85	-	3.85	-	3.85	-	V	
Low Level Input Voltage	$V_{IL}$	-	-	1.5	-	0.3	-	0.3	-	0.3	V	
				3	-	0.9	-	0.9	-	0.9	V	
				5.5	-	1.65	-	1.65	-	1.65	V	
High Level Output Voltage	$V_{OH}$	$V_{IH}$ or $V_{IL}$	-0.05	1.5	1.4	-	1.4	-	1.4	-	V	
			-0.05	3	2.9	-	2.9	-	2.9	-	V	
			-0.05	4.5	4.4	-	4.4	-	4.4	-	V	
			-4	3	2.58	-	2.48	-	2.4	-	V	
			-24	4.5	3.94	-	3.8	-	3.7	-	V	
			-75 (Note 6, 7)	5.5	-	-	3.85	-	-	-	V	
			-50 (Note 6, 7)	5.5	-	-	-	-	3.85	-	V	

**CD54/74AC257, CD54/74ACT257, CD74ACT258**

**DC Electrical Specifications (Continued)**

PARAMETER	SYMBOL	TEST CONDITIONS		V <sub>CC</sub> (V)	25°C		-40°C TO 85°C		-55°C TO 125°C		UNITS
		V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN	MAX	MIN	MAX	MIN	MAX	
Low Level Output Voltage	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.05	1.5	-	0.1	-	0.1	-	0.1	V
			0.05	3	-	0.1	-	0.1	-	0.1	V
			0.05	4.5	-	0.1	-	0.1	-	0.1	V
			12	3	-	0.36	-	0.44	-	0.5	V
			24	4.5	-	0.36	-	0.44	-	0.5	V
			75 (Note 6, 7)	5.5	-	-	-	1.65	-	-	V
			50 (Note 6, 7)	5.5	-	-	-	-	-	1.65	V
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> or GND	-	5.5	-	±0.1	-	±1	-	±1	µA
Three-State Leakage Current	I <sub>OZ</sub>	V <sub>IH</sub> or V <sub>IL</sub> V <sub>O</sub> = V <sub>CC</sub> or GND	-	5.5	-	±0.5	-	±5	-	±10	µA
Quiescent Supply Current MSI	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	-	8	-	80	-	160	µA
<b>ACT TYPES</b>											
High Level Input Voltage	V <sub>IH</sub>	-	-	4.5 to 5.5	2	-	2	-	2	-	V
Low Level Input Voltage	V <sub>IL</sub>	-	-	4.5 to 5.5	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.05	4.5	4.4	-	4.4	-	4.4	-	V
			-24	4.5	3.94	-	3.8	-	3.7	-	V
			-75 (Note 6, 7)	5.5	-	-	3.85	-	-	-	V
			-50 (Note 6, 7)	5.5	-	-	-	-	3.85	-	V
Low Level Output Voltage	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.05	4.5	-	0.1	-	0.1	-	0.1	V
			24	4.5	-	0.36	-	0.44	-	0.5	V
			75 (Note 6, 7)	5.5	-	-	-	1.65	-	-	V
			50 (Note 6, 7)	5.5	-	-	-	-	-	1.65	V
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> or GND	-	5.5	-	±0.1	-	±1	-	±1	µA
Three-State or Leakage Current	I <sub>OZ</sub>	V <sub>IH</sub> or V <sub>IL</sub> V <sub>O</sub> = V <sub>CC</sub> or GND	-	5.5	-	±0.5	-	±5	-	±10	µA
Quiescent Supply Current MSI	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	-	8	-	80	-	160	µA
Additional Supply Current per Input Pin TTL Inputs High 1 Unit Load	ΔI <sub>CC</sub>	V <sub>CC</sub> -2.1	-	4.5 to 5.5	-	2.4	-	2.8	-	3	mA

**NOTES:**

- Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.
- Test verifies a minimum 50Ω transmission-line-drive capability at 85°C, 75Ω at 125°C.

**CD54/74AC257, CD54/74ACT257, CD74ACT258**

**ACT Input Load Table**

INPUT	UNIT LOAD
Data	0.83
S	1.27
OE	1.27

NOTE: Unit load is  $\Delta I_{CC}$  limit specified in DC Electrical Specifications Table, e.g., 2.4mA max at 25°C.

**Switching Specifications** Input  $t_r$ ,  $t_f = 3ns$ ,  $C_L = 50pF$  (Worst Case)

PARAMETER	SYMBOL	$V_{CC}$ (V)	-40°C TO 85°C			-55°C TO 125°C			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	
<b>ACT TYPES</b>									
Propagation Delay, In to Y AC/ACT257	$t_{PLH}$ , $t_{PHL}$	1.5	-	-	106	-	-	117	ns
		3.3 (Note 9)	3.3	-	11.8	3.3	-	13	ns
		5 (Note 10)	2.4	-	8.5	2.3	-	9.3	ns
Propagation Delay, S to Y AC/ACT257	$t_{PLH}$ , $t_{PHL}$	1.5	-	-	153	-	-	168	ns
		3.3	4.8	-	17.1	4.7	-	18.8	ns
		5	3.5	-	12.2	3.4	-	13.4	ns
Propagation Delay, OE to Y AC/ACT257	$t_{PLZ}$ , $t_{PHZ}$ , $t_{PZL}$ , $t_{PZH}$	1.5	-	-	167	-	-	184	ns
		3.3	5.3	-	18.7	5.2	-	20.6	ns
		5	3.8	-	13.4	3.7	-	14.7	ns
Propagation Delay, In to Y 'AC/CD74ACT258	$t_{PLH}$ , $t_{PHL}$	1.5	-	-	91	-	-	100	ns
		3.3	2.9	-	10.2	2.8	-	11.2	ns
		5	2.1	-	7.3	2	-	8	ns
Propagation Delay, S to Y 'AC/CD74ACT258	$t_{PLH}$ , $t_{PHL}$	1.5	-	-	153	-	-	168	ns
		3.3	4.8	-	17.1	4.7	-	18.8	ns
		5	3.5	-	12.2	3.4	-	13.4	ns
Propagation Delay, OE to Y 'AC/CD74ACT258	$t_{PLZ}$ , $t_{PHZ}$ , $t_{PZL}$ , $t_{PZH}$	1.5	-	-	167	-	-	184	ns
		3.3	5.3	-	18.7	5.2	-	20.6	ns
		5	3.8	-	13.4	3.7	-	14.7	ns
Three-State Output Capacitance	$C_O$	-	-	-	15	-	-	15	pF
Input Capacitance	$C_I$	-	-	-	10	-	-	10	pF
Power Dissipation Capacitance	$C_{PD}$ (Note 11)	-	-	130	-	-	130	-	pF
<b>ACT TYPES</b>									
Propagation Delay, In to Y AC/ACT257	$t_{PLH}$ , $t_{PHL}$	5 (Note 10)	2.8	-	9.7	2.7	-	10.7	ns
Propagation Delay, S to Y AC/ACT257	$t_{PLH}$ , $t_{PHL}$	5	4	-	14	3.9	-	15.4	ns

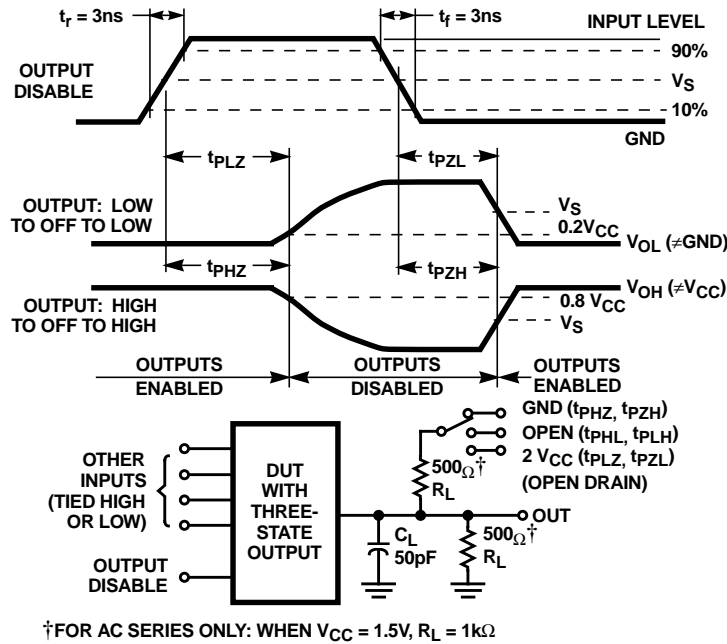
## CD54/74AC257, CD54/74ACT257, CD74ACT258

### Switching Specifications Input $t_r, t_f = 3\text{ns}$ , $C_L = 50\text{pF}$ (Worst Case) (Continued)

PARAMETER	SYMBOL	$V_{CC}$ (V)	-40°C TO 85°C			-55°C TO 125°C			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	
Propagation Delay, $\overline{\text{OE}}$ to Y AC/ACT257	$t_{PLZ}, t_{PHZ}, t_{PZL}, t_{PZH}$	5	4.1	-	14.6	4	-	16.1	ns
Propagation Delay, In to Y 'AC/CD74ACT258	$t_{PLH}, t_{PHL}$	5	2.4	-	8.5	2.3	-	9.3	ns
Propagation Delay, S to Y 'AC/CD74ACT258	$t_{PLH}, t_{PHL}$	5	4	-	14	3.9	-	15.4	ns
Propagation Delay, $\overline{\text{OE}}$ to Y 'AC/CD74ACT258	$t_{PLZ}, t_{PHZ}, t_{PZL}, t_{PZH}$	5	4.1	-	14.6	4	-	16.1	ns
Three-State Output Capacitance	$C_O$	-	-	-	15	-	-	15	pF
Input Capacitance	$C_I$	-	-	-	10	-	-	10	pF
Power Dissipation Capacitance	$C_{PD}$ (Note 11)	-	-	130	-	-	130	-	pF

**NOTES:**

8. Limits tested 100%.
9. 3.3V Min is at 3.6V, Max is at 3V.
10. 5V Min is at 5.5V, Max is at 4.5V.
11.  $C_{PD}$  is used to determine the dynamic power consumption per multiplexer.  
 AC:  $P_D = C_{PD} V_{CC}^2 f_i + \sum (C_L V_{CC}^2 f_o)$   
 ACT:  $P_D = C_{PD} V_{CC}^2 f_i + \sum (C_L V_{CC}^2 f_o) + V_{CC} \Delta I_{CC}$  where  $f_i$  = input frequency,  $f_o$  = output frequency,  $C_L$  = output load capacitance,  $V_{CC}$  = supply voltage.



**FIGURE 1. THREE-STATE PROPAGATION DELAY TIMES AND TEST CIRCUIT**

CD54/74AC257, CD54/74ACT257, CD74ACT258

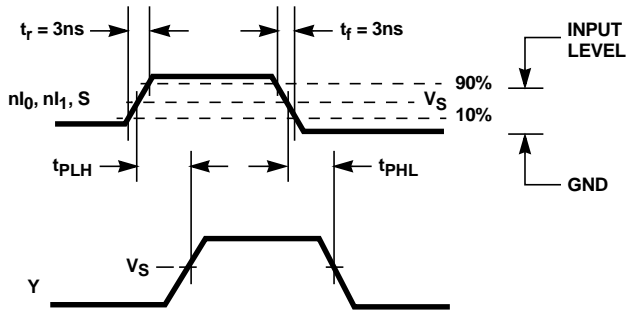


FIGURE 2. INPUTS OR SELECT TO OUTPUT PROPAGATION DELAYS (AC/ACT257)

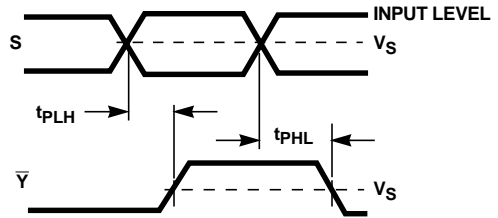
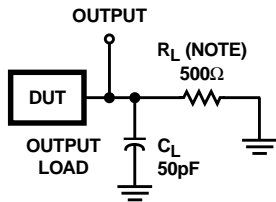


FIGURE 3. SELECT TO OUTPUT PROPAGATION DELAYS (CD74ACT258)



NOTE: For AC Series Only: When  $V_{CC} = 1.5\text{V}$ ,  $R_L = 1\text{k}\Omega$ .

	AC	ACT
Input Level	$V_{CC}$	3V
Input Switching Voltage, $V_S$	$0.5 V_{CC}$	1.5V
Output Switching Voltage, $V_S$	$0.5 V_{CC}$	$0.5 V_{CC}$

FIGURE 4. PROPAGATION DELAY TIMES

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

<b>Products</b>		<b>Applications</b>	
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>	Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>	Automotive	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>	Broadband	<a href="http://www.ti.com/broadband">www.ti.com/broadband</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>	Digital Control	<a href="http://www.ti.com/digitalcontrol">www.ti.com/digitalcontrol</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>	Military	<a href="http://www.ti.com/military">www.ti.com/military</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>	Optical Networking	<a href="http://www.ti.com/opticalnetwork">www.ti.com/opticalnetwork</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>	Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Low Power Wireless	<a href="http://www.ti.com/lpw">www.ti.com/lpw</a>	Telephony	<a href="http://www.ti.com/telephony">www.ti.com/telephony</a>
		Video & Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>
		Wireless	<a href="http://www.ti.com/wireless">www.ti.com/wireless</a>

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2007, Texas Instruments Incorporated



**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CD54AC257F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
CD54ACT257F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
CD74AC257E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74AC257EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74AC257M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC257M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC257M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC257M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC257ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC257MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT257E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74ACT257EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74ACT257M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT257M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT257M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT257M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT257ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT257MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT258M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CD74ACT258M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CD74ACT258M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CD74ACT258M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CD74ACT258ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CD74ACT258MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

---

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**



**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74AC257M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74ACT257M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74ACT257M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74ACT258M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74AC257M96	SOIC	D	16	2500	333.2	345.9	28.6
CD74ACT257M96	SOIC	D	16	2500	346.0	346.0	33.0
CD74ACT257M96	SOIC	D	16	2500	333.2	345.9	28.6
CD74ACT258M96	SOIC	D	16	2500	333.2	345.9	28.6

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

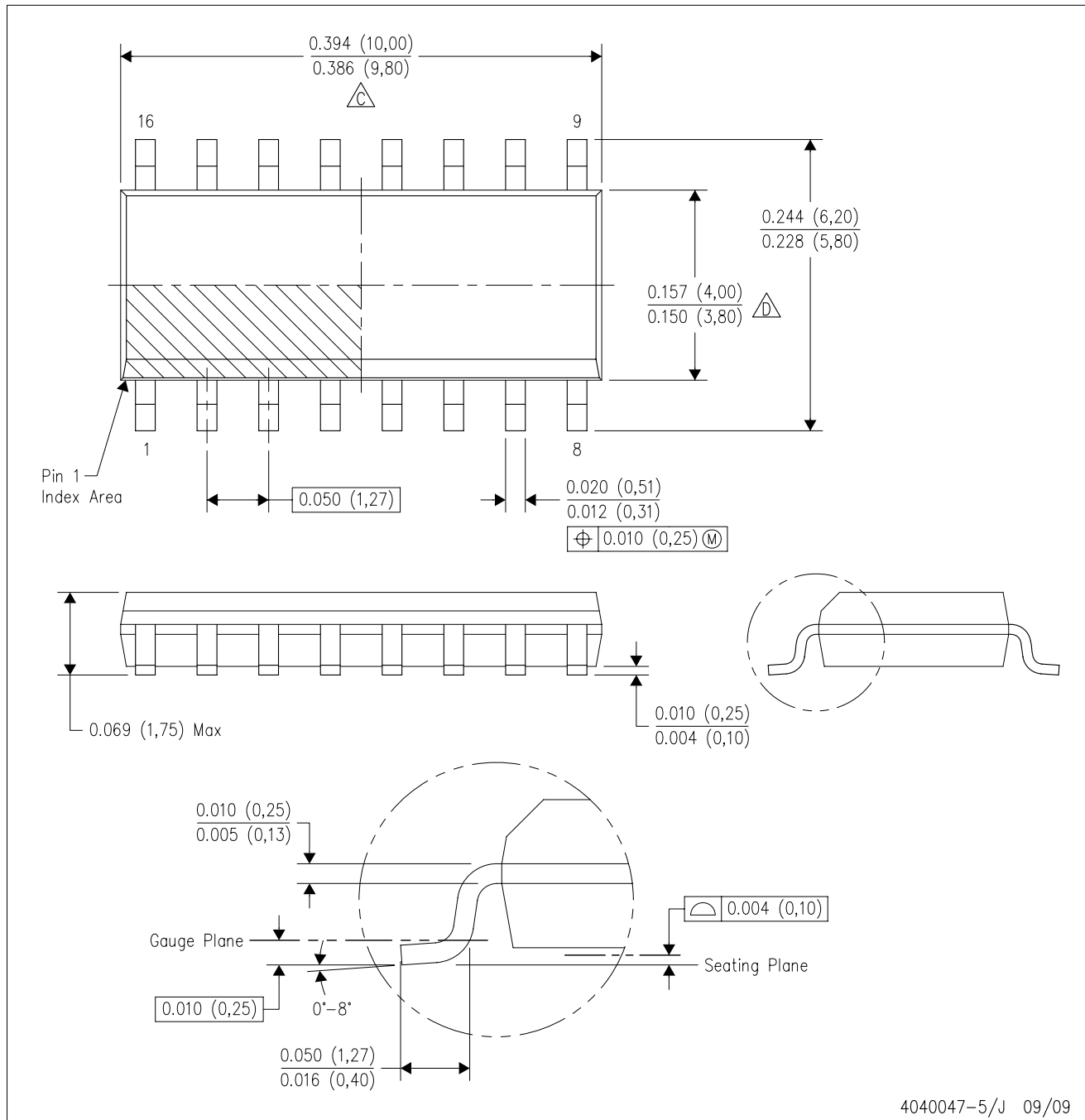


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
  - E. Reference JEDEC MS-012 variation AC.

D(R-PDSO-G16)



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Refer to IPC7351 for alternate board design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.



**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CD54AC257F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
CD54ACT257F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
CD74AC257E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74AC257EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74AC257M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC257M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC257M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC257M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC257ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC257MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT257E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74ACT257EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74ACT257M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT257M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT257M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT257M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT257ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT257MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT258M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CD74ACT258M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CD74ACT258M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CD74ACT258M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CD74ACT258ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CD74ACT258MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

---

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74AC257M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74ACT257M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74ACT257M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74ACT258M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74AC257M96	SOIC	D	16	2500	333.2	345.9	28.6
CD74ACT257M96	SOIC	D	16	2500	367.0	367.0	38.0
CD74ACT257M96	SOIC	D	16	2500	333.2	345.9	28.6
CD74ACT258M96	SOIC	D	16	2500	333.2	345.9	28.6

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040047-6/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  -  C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  -  D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>

### TI E2E Community

[e2e.ti.com](http://e2e.ti.com)